



Final Product Change Notification

202303023F01 : i.MX31_Auto molding compound change from G770FL to G770SFL

Note: This notice is NXP Company Proprietary.

Issue Date: Apr 08, 2023 **Effective date:** Jul 07, 2023

Change Category

- | | | | | |
|--|---|--|--|---|
| <input type="checkbox"/> Wafer
Fab
Process | <input type="checkbox"/> Assembly
Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test
Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer
Fab
Materials | <input checked="" type="checkbox"/> Assembly
Materials | <input type="checkbox"/> Mechanical
Specification | <input type="checkbox"/> Test
Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer
Fab
Location | <input type="checkbox"/> Assembly
Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input type="checkbox"/> Test
Location | <input type="checkbox"/> Electrical
spec./Test
coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PCN Overview

Description

NXP Semiconductors is announcing the successful qualification of molding compound change from G770FL to G770SFL (low alpha) for i.MX31 AUTO 19*19 BGA parts. G770SFL (low alpha) had better performance than G770FL on SER failure rate.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-11

Reason

Molding compound change from G770FL to G770SFL (low alpha) will improve SER performance. Molding compound G770FL and G770SFL (low alpha) have same composition. G770SFL (low alpha) molding compound has better control on alpha particle than G770FL.

Identification of Affected Products

Product identification does not change

Product Availability

Sample Information

Samples are available upon request

Samples for KCIMX31CVMN4D are available from May 29, 2023.

For samples with other part numbers, NXP will deliver within 8 weeks after we receive the request.

Production

Planned first shipment Aug 01, 2023

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification: [view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by May 08, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Cathy Chen
Position	Product Engineer
e-mail address	cathy.chen@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006-2023 NXP Semiconductors. All rights reserved.